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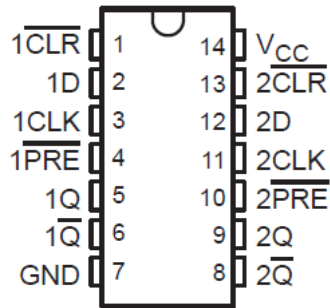
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3 Revision History

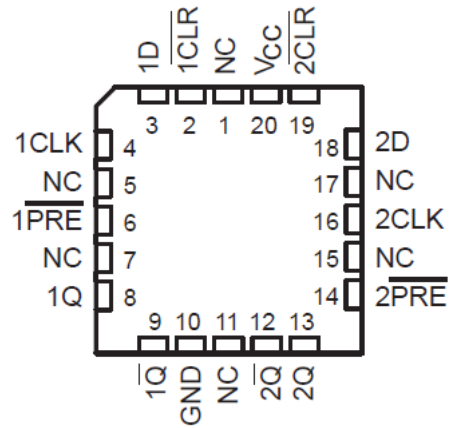
注：以前版本的页码可能与当前版本的页码不同

| Changes from Revision F (February 2022) to Revision G (October 2022) | Page |
|--|-------------|
| • Increased R ^θ JA for packages: D (86 to 138.7); N (80 to 103.8); NS (76 to 129.3); PW (113 to 157.6)..... | 4 |

4 Pin Configuration and Functions



J, W, D, DB, N, NS, or PW package
14-Pin CDIP, CFP, SOIC, SSOP, PDIP, SO, or TSSOP
Top View



NC - No internal connection

FK Package
20-Pin LCCC
Top View

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|------------------|---|--|------|------|
| V _{CC} | Supply voltage range | - 0.5 | 7 | V |
| I _{IK} | Input clamp current ⁽²⁾ | V _I < 0 or V _I > V _{CC} | ± 20 | mA |
| I _{OK} | Output clamp current ⁽²⁾ | V _O < 0 or V _O > V _{CC} | ± 20 | mA |
| I _O | Continuous output current | V _O = 0 to V _{CC} | ± 25 | mA |
| | Continuous current through V _{CC} or GND | | ± 50 | mA |
| T _J | Junction temperature | | 150 | °C |
| T _{stg} | Storage temperature range | - 65 | 150 | °C |

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Recommended Operating Conditions⁽¹⁾

| | | SN54HCT74 ⁽²⁾ | | | SN74HCT74 | | | UNIT |
|-----------------|---------------------------------|----------------------------------|-----|-----------------|-----------|-----|-----------------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V _{CC} | Supply voltage | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| V _{IH} | High-level input voltage | V _{CC} = 4.5 V to 5.5 V | | 2 | 2 | | | V |
| V _{IL} | Low-level input voltage | V _{CC} = 4.5 V to 5.5 V | | 0.8 | 0.8 | | | V |
| V _I | Input voltage | 0 | | V _{CC} | 0 | | V _{CC} | V |
| V _O | Output voltage | 0 | | V _{CC} | 0 | | V _{CC} | V |
| Δt/Δv | Input transition rise/fall time | | | 500 | | | 500 | ns |
| T _A | Operating free-air temperature | -55 | | 125 | -40 | | 85 | °C |

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).
- (2) SN54HCT74 is in product preview.

5.3 Thermal Information

| THERMAL METRIC | | D (SOIC) | DB (SSOP) | N (PDIP) | NS (SO) | PW (TSSOP) | UNIT |
|------------------------|---|----------|-----------|----------|---------|------------|------|
| | | 14 PINS | 14 PINS | 14 PINS | 14 PINS | 14 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance ⁽¹⁾ | 138.7 | 109.8 | 61.1 | 88.4 | 114.7 | °C/W |
| R _{θJC (top)} | Junction-to-case (top) thermal resistance | 93.8 | 54.7 | 48.9 | 46 | 44.3 | °C/W |
| R _{θJB} | Junction-to-board thermal resistance | 94.7 | 58.6 | 40.9 | 48.9 | 57.6 | °C/W |
| Ψ _{JT} | Junction-to-top characterization parameter | 49.1 | 15.5 | 28.5 | 13.8 | 4.8 | °C/W |
| Ψ _{JB} | Junction-to-board characterization parameter | 94.3 | 58 | 40.6 | 48.4 | 57 | °C/W |
| R _{θJC (bot)} | Junction-to-case (bottom) thermal resistance | N/A | N/A | N/A | N/A | N/A | °C/W |

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | V _{CC} | T _A = 25°C | | | SN54HCT74 ⁽²⁾ | | SN74HCT74 | | UNIT |
|---------------------------------|--|--------------------------|-----------------|-----------------------|-------|------|--------------------------|-------|-----------|-------|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | V _I = V _{IH} or V _{IL} | I _{OH} = -20 μA | 4.5 V | 4.4 | 4.499 | | 4.4 | | 4.4 | V | |
| | | I _{OH} = -4 mA | | 3.98 | 4.3 | | 3.7 | | 3.84 | | |
| V _{OL} | V _I = V _{IH} or V _{IL} | I _{OL} = 20 μA | 4.5 V | | 0.001 | 0.1 | | 0.1 | | 0.1 | V |
| | | I _{OL} = 4 mA | | | 0.17 | 0.26 | | 0.4 | | 0.33 | |
| I _I | V _I = V _{CC} or 0 | | 5.5 V | | ±0.1 | ±100 | | ±1000 | | ±1000 | nA |
| I _{CC} | V _I = V _{CC} or 0, | I _O = 0 | 5.5 V | | | 4 | | 80 | | 40 | μA |
| ΔI _{CC} ⁽¹⁾ | One input at 0.5 V or 2.4 V, Other inputs at 0 or V _{CC} | | 5.5 V | | 1.4 | 2.4 | | 3 | | 2.9 | mA |
| C _i | | | 4.5 V to 5.5 V | | 3 | 10 | | 10 | | 10 | pF |

(1) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

(2) SN54HCT74 is in product preview.

5.5 Timing Requirements

overrecommended operating free-air temperature range (unless otherwise noted)

| | | V _{CC} | T _A = 25°C | | SN54HCT74 ⁽¹⁾ | | SN74HCT74 | | UNIT |
|--------------------|-----------------------------|---|-----------------------|-----|--------------------------|-----|-----------|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| f _{clock} | Clock frequency | 4.5 V | | 27 | | 18 | | 22 | MHz |
| | | 5.5 V | | 30 | | 20 | | 24 | |
| t _w | Pulse duration | PRE or $\overline{\text{CLR}}$ low | 4.5 V | 16 | | 24 | | 20 | ns |
| | | | 5.5 V | 14 | | 21 | | 18 | |
| | | CLK high or low | 4.5 V | 18 | | 27 | | 23 | |
| | | | 5.5 V | 16 | | 24 | | 21 | |
| t _{su} | Setup time before CLK ↑ | Data | 4.5 V | 12 | | 18 | | 15 | ns |
| | | | 5.5 V | 11 | | 16 | | 14 | |
| | | PRE or $\overline{\text{CLR}}$ inactive | 4.5 V | 0 | | 0 | | 0 | |
| | | | 5.5 V | 0 | | 0 | | 0 | |
| t _h | Hold time, data after CLK ↑ | 4.5 V | 0 | | 0 | | 0 | ns | |
| | | 5.5 V | 0 | | 0 | | 0 | | |

(1) SN54HCT74 is in product preview.

5.6 Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see [Parameter Measurement Information](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V_{CC} | $T_A = 25^\circ\text{C}$ | | | SN54HCT74 ⁽¹⁾ | | SN74HCT74 | | UNIT |
|-----------|--------------|----------------|----------|--------------------------|-----|-----|--------------------------|-----|-----------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| f_{max} | | | 4.5 V | 27 | 40 | | 18 | | 22 | MHz | |
| | | | 5.5 V | 30 | 46 | | 20 | | 24 | | |
| t_{pd} | PRE or CLR | Q or \bar{Q} | 4.5 V | | 21 | 35 | | 53 | | 44 | ns |
| | | | 5.5 V | | 17 | 31 | | 48 | | 40 | |
| | CLK | Q or \bar{Q} | 4.5 V | | 20 | 28 | | 42 | | 35 | |
| | | | 5.5 V | | 18 | 25 | | 38 | | 31 | |
| t_t | | Q or \bar{Q} | 4.5 V | | 8 | 15 | | 22 | | 19 | ns |
| | | | 5.5 V | | 7 | 14 | | 20 | | 17 | |

(1) SN54HCT74 is in product preview.

5.7 Operating Characteristics

$T_A = 25^\circ\text{C}$

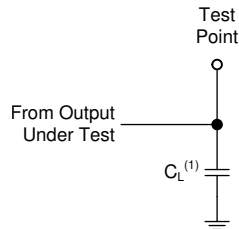
| PARAMETER | | TEST CONDITIONS | TYP | UNIT |
|-----------|---|-----------------|-----|------|
| C_{pd} | Power dissipation capacitance per flip-flop | No load | 35 | pF |

6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f < 6 \text{ ns}$.

For clock inputs, f_{max} is measured when the input duty cycle is 50%.

The outputs are measured one at a time with one input transition per measurement.



(1) C_L includes probe and test-fixture capacitance.

图 6-1. Load Circuit for Push-Pull Outputs

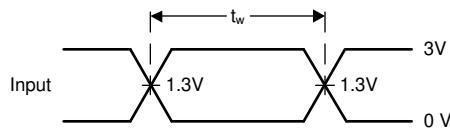


图 6-2. Voltage Waveforms, TTL-Compatible CMOS Inputs Pulse Duration

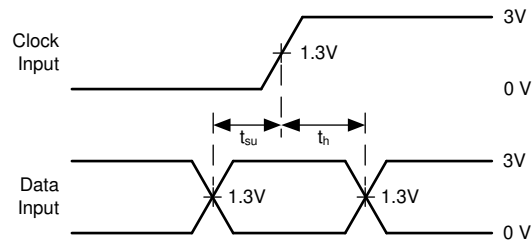
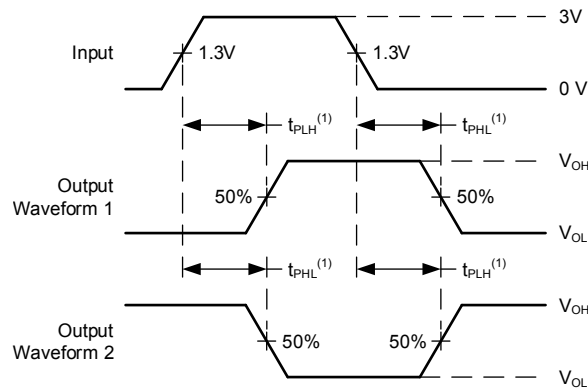


图 6-3. Voltage Waveforms, TTL-Compatible CMOS Inputs Setup and Hold Times



(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd} .

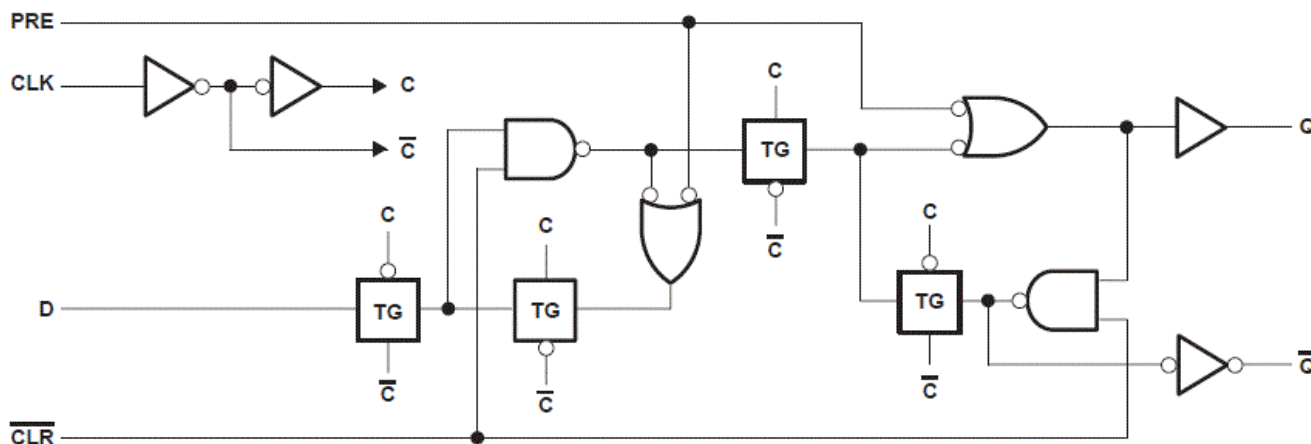
图 6-4. Voltage Waveforms, Propagation Delays for TTL-Compatible Inputs

7 Detailed Description

7.1 Overview

The ' HCT74 devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the data (D) input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input may be changed without affecting the levels at the outputs.

7.2 Functional Block Diagram



7.3 Device Functional Modes

表 7-1. Function Table

| INPUTS | | | | OUTPUT | |
|--------|-----|-----|---|------------------|------------------|
| PRE | CLR | CLK | D | Q | \overline{Q} |
| L | H | X | X | H | L |
| H | L | X | X | L | H |
| L | L | X | X | H ⁽¹⁾ | H ⁽¹⁾ |
| H | H | ↑ | H | H | L |
| H | H | ↑ | L | L | H |
| H | H | L | X | Q ₀ | \overline{Q}_0 |

- (1) This configuration is nonstable; that is, it does not persist when \overline{PRE} or \overline{CLR} returns to its inactive (high) level.

8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

9 Layout

9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices, inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

10.2 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.5 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|------------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| JM38510/65352B2A | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 65352B2A | Samples |
| JM38510/65352BCA | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 65352BCA | Samples |
| JM38510/65352BDA | ACTIVE | CFP | W | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 65352BDA | Samples |
| M38510/65352B2A | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 65352B2A | Samples |
| M38510/65352BCA | ACTIVE | CDIP | J | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 65352BCA | Samples |
| M38510/65352BDA | ACTIVE | CFP | W | 14 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | JM38510/ 65352BDA | Samples |
| SN74HCT74D | ACTIVE | SOIC | D | 14 | 50 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCT74 | Samples |
| SN74HCT74DBR | ACTIVE | SSOP | DB | 14 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HT74 | Samples |
| SN74HCT74DR | ACTIVE | SOIC | D | 14 | 2500 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 85 | HCT74 | Samples |
| SN74HCT74DRE4 | ACTIVE | SOIC | D | 14 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCT74 | Samples |
| SN74HCT74DT | ACTIVE | SOIC | D | 14 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCT74 | Samples |
| SN74HCT74N | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74HCT74N | Samples |
| SN74HCT74NE4 | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74HCT74N | Samples |
| SN74HCT74NSR | ACTIVE | SO | NS | 14 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCT74 | Samples |
| SN74HCT74PW | ACTIVE | TSSOP | PW | 14 | 90 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HT74 | Samples |
| SN74HCT74PWR | ACTIVE | TSSOP | PW | 14 | 2000 | RoHS & Green | NIPDAU SN | Level-1-260C-UNLIM | -40 to 85 | HT74 | Samples |
| SN74HCT74PWT | ACTIVE | TSSOP | PW | 14 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HT74 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

⁽³⁾ **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ **Lead finish/Ball material** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HCT74, SN74HCT74 :

● Catalog : [SN74HCT74](#)

● Military : [SN54HCT74](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74HCT74DBR | SSOP | DB | 14 | 2000 | 330.0 | 16.4 | 8.35 | 6.6 | 2.4 | 12.0 | 16.0 | Q1 |
| SN74HCT74DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.6 | 9.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCT74DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCT74DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCT74DT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCT74NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74HCT74PWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.85 | 5.45 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74HCT74PWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74HCT74PWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74HCT74PWT | TSSOP | PW | 14 | 250 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74HCT74DBR | SSOP | DB | 14 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74HCT74DR | SOIC | D | 14 | 2500 | 366.0 | 364.0 | 50.0 |
| SN74HCT74DR | SOIC | D | 14 | 2500 | 356.0 | 356.0 | 35.0 |
| SN74HCT74DR | SOIC | D | 14 | 2500 | 356.0 | 356.0 | 35.0 |
| SN74HCT74DT | SOIC | D | 14 | 250 | 210.0 | 185.0 | 35.0 |
| SN74HCT74NSR | SO | NS | 14 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74HCT74PWR | TSSOP | PW | 14 | 2000 | 366.0 | 364.0 | 50.0 |
| SN74HCT74PWR | TSSOP | PW | 14 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74HCT74PWR | TSSOP | PW | 14 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74HCT74PWT | TSSOP | PW | 14 | 250 | 356.0 | 356.0 | 35.0 |

TUBE


*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|------------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| JM38510/65352B2A | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| JM38510/65352BDA | W | CFP | 14 | 1 | 506.98 | 26.16 | 6220 | NA |
| M38510/65352B2A | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| M38510/65352BDA | W | CFP | 14 | 1 | 506.98 | 26.16 | 6220 | NA |
| SN74HCT74D | D | SOIC | 14 | 50 | 506.6 | 8 | 3940 | 4.32 |
| SN74HCT74N | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74HCT74N | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74HCT74NE4 | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74HCT74NE4 | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74HCT74PW | PW | TSSOP | 14 | 90 | 530 | 10.2 | 3600 | 3.5 |

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

J 14

GENERIC PACKAGE VIEW
CDIP - 5.08 mm max height
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

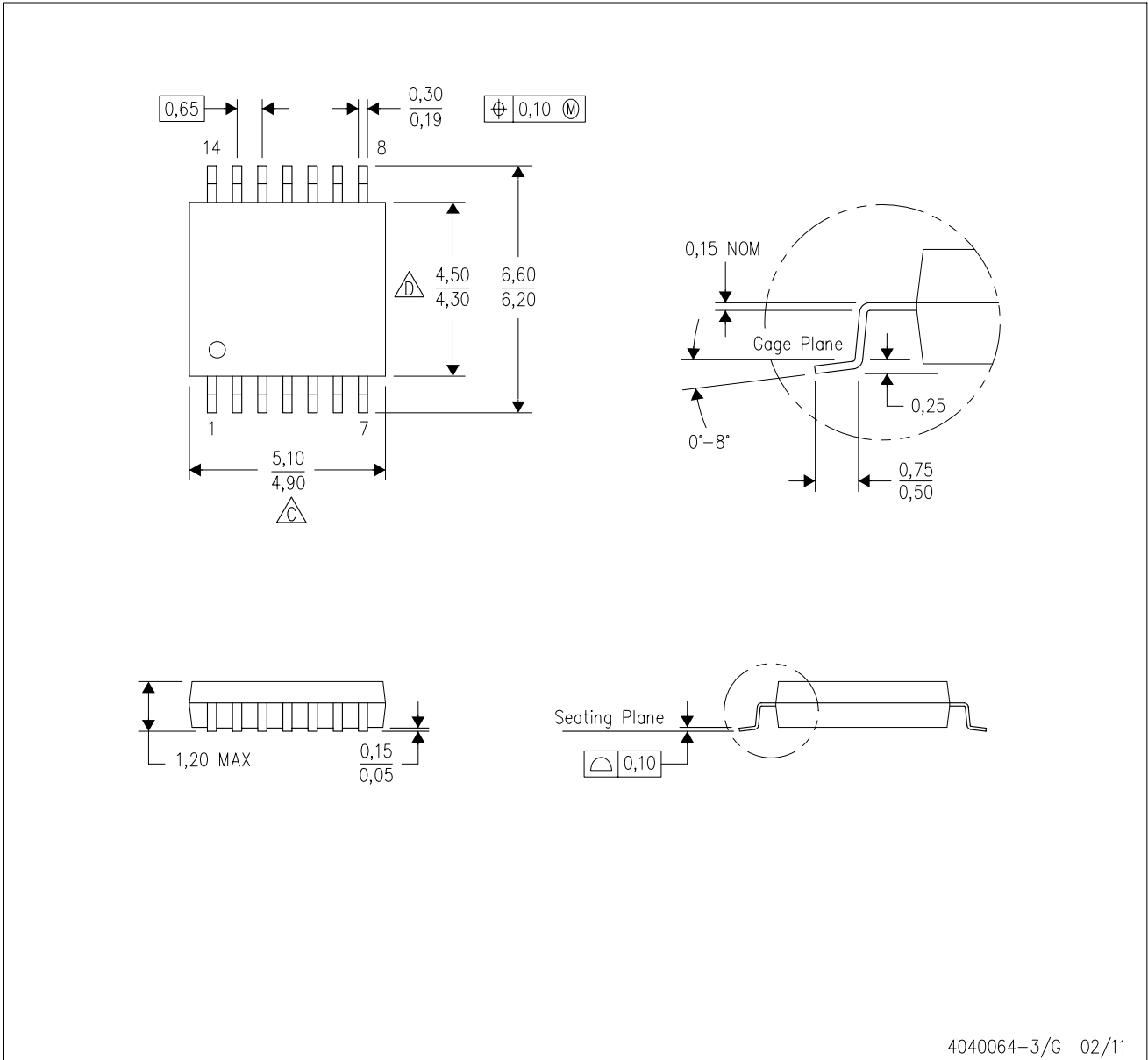
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/G 08/15

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

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